

7. Technical Parameter

Item	Specification	X1.25	X1.56	X1.95
Module Parameter	Pixel Pitch (mm)	1.25	1.56	1.95
	Pixel Structure	COB 1R1G1B Flip Chip Process		
	Pixel Density(dot//m2)	640,000	409,600	262,144
	Module Size(W*H)(mm)	250*250	250*250	250*250
	Backshell Material	No Backshell		
	Module Resolution(W*H)(dot)	200*200	160*160	128*128
	Maximum Current(A)	5	5	5
	Supply Voltage(V)	4.2	4.2	4.2
	Scanning Method	1/50	1/40	1/16
	Refresh Frequency(Hz)	≥3840	≥3840	≥7680
	Illumination(cd//m2)	500~600	500~600	1500~1800
	Driver IC	Constant Current Drive		
	Contrast Ratio	≥10000:1	≥10000:1	≥10000:1
Cabinet Parameter	Cabinet Size(W*H*D)(mm)	500*500*50 (Supports mixed-size splicing) 1000*250*50 / 1000*500*50/500*250*50/250*500*50		
	Cabinet Material	Die Casting Aluminum		
	Cabinet Weight(kg)	6.4/8.9/11.5/4.3		
	Enclosure Connection Method	Screw Fixing		
	Installation/Maintenance Methods	Front and Rear Installation/Front Maintenance		
	Color Temperature /Luminance Uniformity	3200-9300K; ≥98%		
	Chromatic Uniformity	±0.003Cx,Cy		
	Horizontal/Vertical View	≥170°		
	Single-point Color Correction	Yes		
	Single Point Brightness Correction	Yes		
	Standard Receiver Card	JichuangTX40-PRO		
	Frame Rate(Hz)	50/60		
	Protection Level	IP30		
	Signal Interface Mode	HDMI		
	Power Interface Method	Three Pole Flat Connector		
	Input Voltage Range AC(V)	100-240		
	Peak Power Consumption(W/m2)	≤350	≤350	≤440
	Average Power Consumption(W//m2)	≤170	≤170	≤220
	Working Temperature and Humidity Range	-20°C~+50°C, 10%~95%RH		
	Storage Temperature and Humidity Range	-40~+70°C, 10%~95%RH		
	Service Life(H)	≥100000		
	Mean Time Between Failure(H)	≥10000		